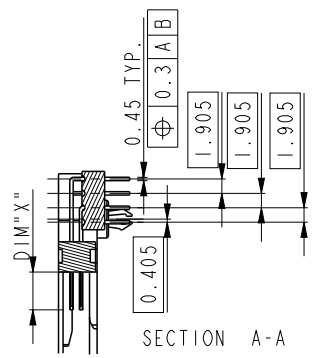
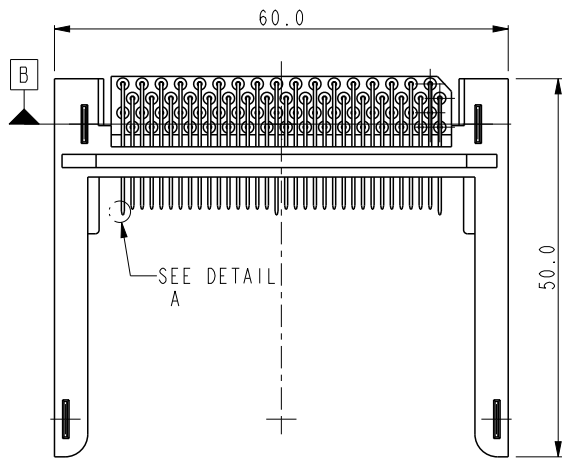
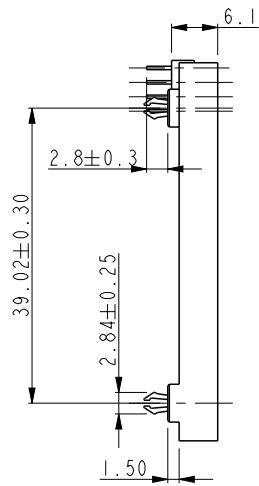
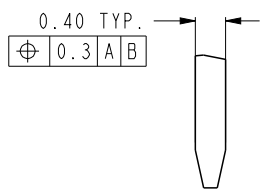


PRODUCT NO.	STAND OFF
10120698-015LF	1.5MM

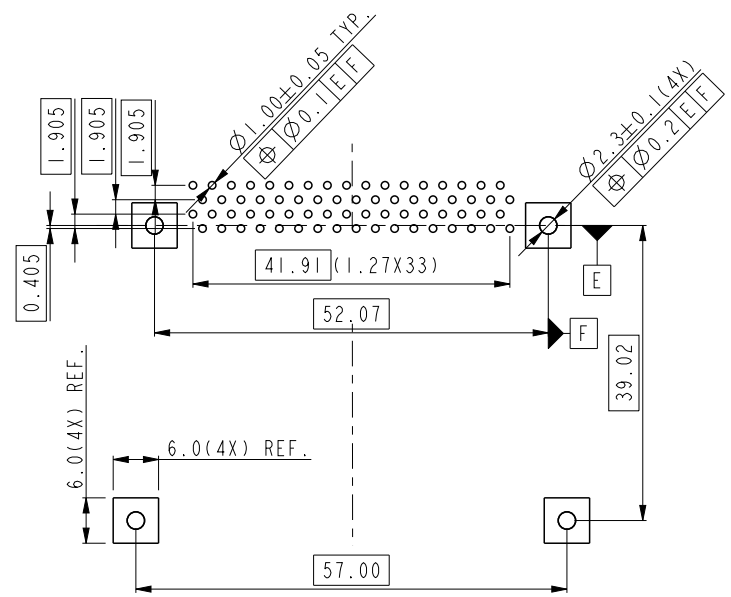
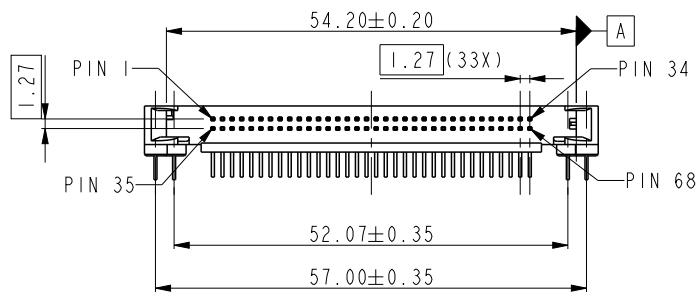


- NOTE:
- MATERIAL: HOUSING: HIGH TEMPERATURE THERMOPLASTIC
LOCATOR: HIGH TEMPERATURE THERMOPLASTIC
PIN- COPPER ALLOY
 - FINISH (PIN)
 - ALL OVER : Ni UNDER PLATING 1.27um THICK MIN.
 - CONTACT AREA: Au 0.075um THK MIN.
 - PURE TIN PLATING 2.5um THICK MIN.
 - IF LEAD FREE P/N, THE HOUSING WILL WITHSTAND EXPOSURE TO 260°C PEAK TEMPERATURE FOR 10 SECONDS IN A WAVE SOLDER APPLICATION WITH A 1.60MM MINIMUM THICK CIRCUIT BOARD.
 - LEAD FREE PRODUCT MEETS EUROPEAN UNION DIRECTIVES AND OTHER COUNTRY REGULATIONS AS DISCRIBLED IN GS-22-008
 - PRODUCT SPEC: 110-263

DIM X			
DIM	4.25±0.1	3.5±0.1	5.0±0.1
PIN NUMBER	OTHERS	36,67	1, 17, 34, 35, 51, 68



DETAIL A
SCALE 10.000



RECOMMENDED PCB LAYOUT

spec ref	-	dr	Su-Hua Miao	2012/11/20	projection	MM	size	A4	scale	1.000
tolerance std	ISO 406 ISO 1101	eng	Su-Hua Miao	2012/11/21			ecn no	-	rel level	Released
TOLERANCES UNLESS OTHERWISE SPECIFIED		chr	-	-						
surface	ISO 1302	appr	Rick Bian	2012/11/21	product family	-	rev			
<input checked="" type="checkbox"/> linear <input type="checkbox"/> angular	0.X	±0.30		title 68POS 3.3V PCMCIA ASSEMBLY 50MM HALOGEN-FREE PRODUCT	dwg no 10120698	rev A	sheet 1 of 1			
	0.XX	±0.15								
0.XXX	±0.08									
0°	±2°	www.fci.com	cat. no.	-	Product - Customer Drw					

PrdE File - REV C - 2009-06-09



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